UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF CORRECTION**

PATENT NO.

: 7.084,455 B2

Page 1 of 2

APPLICATION NO.: 10/770045

DATED

: August 1, 2006

INVENTOR(S)

: Richard A. Blanchard

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, item [57]

Abstract, line 18, after "the", change "another" to --other--.

Col. 3, line 12, begin a new paragraph and add

--Accordingly, it would be desirable to provide a method of fabricating the MOSFET structure shown in FIG. 3 that requires a minimum number of epitaxial deposition steps so that it can be produced less expensively while also allowing sufficient control of process parameters so that a high degree of charge compensation can be achieved in adjacent columns of opposite doping type in the drift region of the device.--

Col. 3, line 33, after "the", change "another" to --other--.

Col. 5, line 9, after "layer", change "502" to --501--.

Col. 5, line 17, after "trench", change "5201" to --5201--.

Col. 5, line 25, after "layer", change "524," to --5241--.

Col. 6, line 31, after "encompasses", delete --a--.

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APPLICATION NO.: 10/770045

DATED INVENTOR(S) : August 1, 2006 : Richard A. Blanchard

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Col. 6, line 39, after first word "The", change "polysilcon" to --polysilicon--.

Signed and Sealed this

Thirteenth Day of November, 2007

JON W. DUDAS

Director of the United States Patent and Trademark Office